200mm Fully-Automatic Wafer Mounter
RAD-2500F/8

Outline
- Fully-automatic wafer mounter for pre-cut dicing tapes.
- Consists of alignment function and TTC* system which reduces voids at lamination.

*TTC (Tape Tension Control) System: The TTC is a cutting-edge system, in which a microcomputer controls tape tension. It enables the tape to be laminated according to the tape type and back-end processing conditions. On the fully-automatic type, tape application torque and torque curve can be set and registered with the equipment’s touch screen.

Option
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)

Suitable Tapes
- Pre-cut dicing tape: Adwill D series, G series
- Dicing die bonding tape: Adwill LE Tape

External View

Facility

Power Supply
- Voltage: AC200-230V ±10% (AC190-253V)
- Frequency: 50/60Hz
- Phase: single phase
- Power consumption: 1.0kW

Air Supply
- Air pressure: 0.5-0.8MPa
- Air consumption: >400L/min (ANR)

Applicable Wafer Size
- 150mm, 200mm
- Please inquire about options for compatibility with specific wafer sizes.

Size
- Width: 1,360mm
- Depth: 1,512mm
- Height: 1,350mm
- (excluding the signal tower)

Weight
- 1,000kg

UPH
- 100 wafers/hour

Top View
Front View
Right Side View

Adwill®
will give you the Advantage

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